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Express Mail No.: **EL 451 599 709 US**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Mohammad Eslamy

Application No.: 09/938,075

Group Art Unit: 2815

Filed: August 23, 2001

Examiner: Joseph H. Nguyen

For: SYMMETRIC STACK UP
STRUCTURE FOR ORGANIC
BGA CHIP CARRIERS

Attorney Docket No.: 9818-055-999

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RESPONSE TO THE OFFICE ACTION DATED NOVEMBER 29, 2002

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated November 29, 2002, entry of the following amendments and remarks is respectfully requested.

AMENDMENT

IN THE CLAIMS:

A marked up version of the revised claims, showing insertions and deletions, is included in the Appendix attached hereto.

Please rewrite the pending claims as follows:

- B'
9. (Twice Amended) A semiconductor chip carrier comprising:
- a primary substrate;
 - a metal heat sink plate, whose thermal coefficient of expansion is substantially different from that of said primary substrate, having a first side and an opposing second side where said primary substrate is attached to said first side;
 - a supplemental substrate being attached to said second side of said metal heat sink plate, wherein said metal heat sink plate is between said primary substrate and said supplemental substrate; and

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